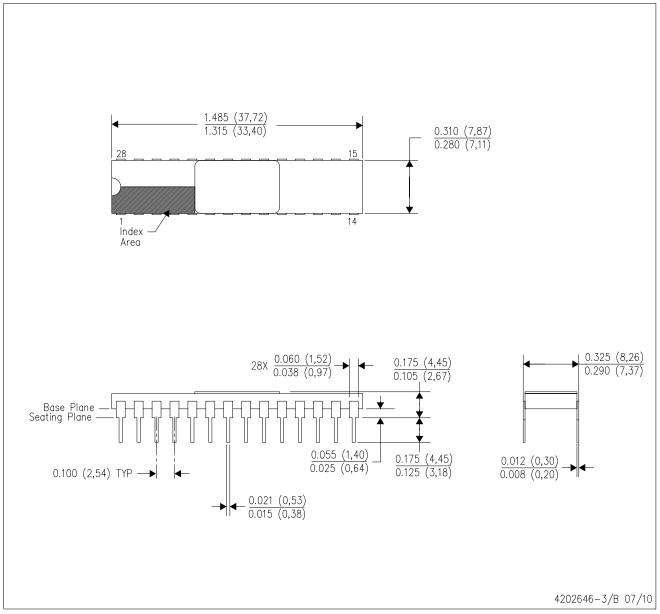
## JDJ (R-CDIP-T28)

## CERAMIC DUAL IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
- D. This package is hermetically sealed with a metal lid.
- E. The leads are gold plated and can be solderdipped.
- F. Leads not shown for clarity purposes.
- G. Lid and heat sink are connected to GND leads.



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